



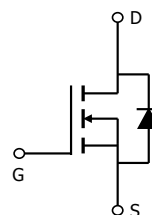
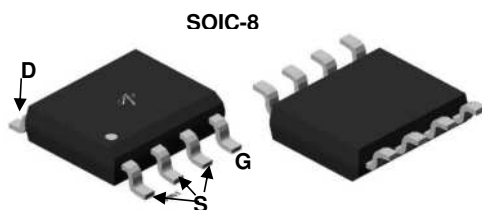
### General Description

The AO4476A combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is suitable for use as a high side switch in SMPS and general purpose applications.

### Product Summary

|                                    |                  |
|------------------------------------|------------------|
| $V_{DS}$                           | 30V              |
| $I_D$ (at $V_{GS}=10V$ )           | 15A              |
| $R_{DS(ON)}$ (at $V_{GS}=10V$ )    | < 7.7m $\Omega$  |
| $R_{DS(ON)}$ (at $V_{GS} = 4.5V$ ) | < 10.8m $\Omega$ |

100% UIS Tested  
100%  $R_g$  Tested



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter                                      | Symbol           | Maximum    | Units            |
|------------------------------------------------|------------------|------------|------------------|
| Drain-Source Voltage                           | $V_{DS}$         | 30         | V                |
| Gate-Source Voltage                            | $V_{GS}$         | $\pm 20$   | V                |
| Continuous Drain Current                       | $I_D$            | 15         | A                |
| $T_A=25^\circ\text{C}$                         |                  |            |                  |
| Current                                        |                  | 12         |                  |
| $T_A=70^\circ\text{C}$                         |                  |            |                  |
| Pulsed Drain Current <sup>C</sup>              | $I_{DM}$         | 110        |                  |
| Avalanche Current <sup>C</sup>                 | $I_{AS}, I_{AR}$ | 27         | A                |
| Avalanche energy $L=0.1\text{mH}$ <sup>C</sup> | $E_{AS}, E_{AR}$ | 36         | mJ               |
| Power Dissipation <sup>B</sup>                 | $P_D$            | 3.1        | W                |
| $T_A=25^\circ\text{C}$                         |                  |            |                  |
| $T_A=70^\circ\text{C}$                         |                  | 2          |                  |
| Junction and Storage Temperature Range         | $T_J, T_{STG}$   | -55 to 150 | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter                                  | Symbol          | Typ | Max | Units              |
|--------------------------------------------|-----------------|-----|-----|--------------------|
| Maximum Junction-to-Ambient <sup>A</sup>   | $R_{\theta JA}$ | 31  | 40  | $^\circ\text{C/W}$ |
| $t \leq 10\text{s}$                        |                 |     |     |                    |
| Maximum Junction-to-Ambient <sup>A,D</sup> | $R_{\theta JA}$ | 59  | 75  | $^\circ\text{C/W}$ |
| Steady-State                               |                 |     |     |                    |
| Maximum Junction-to-Lead                   | $R_{\theta JL}$ | 16  | 24  | $^\circ\text{C/W}$ |
| Steady-State                               |                 |     |     |                    |

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

| Symbol                      | Parameter                             | Conditions                                                                              | Min  | Typ       | Max       | Units |
|-----------------------------|---------------------------------------|-----------------------------------------------------------------------------------------|------|-----------|-----------|-------|
| <b>STATIC PARAMETERS</b>    |                                       |                                                                                         |      |           |           |       |
| BV <sub>DSS</sub>           | Drain-Source Breakdown Voltage        | I <sub>D</sub> =250μA, V <sub>GS</sub> =0V                                              | 30   |           |           | V     |
| I <sub>DSS</sub>            | Zero Gate Voltage Drain Current       | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V<br>T <sub>J</sub> =55°C                       |      |           | 1<br>5    | μA    |
| I <sub>GSS</sub>            | Gate-Body leakage current             | V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V                                             |      |           | 100       | nA    |
| V <sub>GS(th)</sub>         | Gate Threshold Voltage                | V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250μA                                  | 1.5  | 1.98      | 2.5       | V     |
| I <sub>D(ON)</sub>          | On state drain current                | V <sub>GS</sub> =10V, V <sub>DS</sub> =5V                                               | 110  |           |           | A     |
| R <sub>DS(ON)</sub>         | Static Drain-Source On-Resistance     | V <sub>GS</sub> =10V, I <sub>D</sub> =15A<br>T <sub>J</sub> =125°C                      |      | 6.4<br>10 | 7.7<br>12 | mΩ    |
|                             |                                       | V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A                                              |      | 8.6       | 10.8      | mΩ    |
| g <sub>FS</sub>             | Forward Transconductance              | V <sub>DS</sub> =5V, I <sub>D</sub> =15A                                                |      | 45        |           | S     |
| V <sub>SD</sub>             | Diode Forward Voltage                 | I <sub>S</sub> =1A, V <sub>GS</sub> =0V                                                 |      | 0.74      | 1         | V     |
| I <sub>S</sub>              | Maximum Body-Diode Continuous Current |                                                                                         |      |           | 4         | A     |
| <b>DYNAMIC PARAMETERS</b>   |                                       |                                                                                         |      |           |           |       |
| C <sub>iss</sub>            | Input Capacitance                     | V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz                                       | 920  | 1150      | 1380      | pF    |
| C <sub>oss</sub>            | Output Capacitance                    |                                                                                         | 125  | 180       | 235       | pF    |
| C <sub>rss</sub>            | Reverse Transfer Capacitance          |                                                                                         | 60   | 105       | 150       | pF    |
| R <sub>g</sub>              | Gate resistance                       | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz                                        | 0.55 | 1.1       | 1.65      | Ω     |
| <b>SWITCHING PARAMETERS</b> |                                       |                                                                                         |      |           |           |       |
| Q <sub>g</sub> (10V)        | Total Gate Charge                     | V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =15A                         | 16   | 20        | 24        | nC    |
| Q <sub>g</sub> (4.5V)       | Total Gate Charge                     |                                                                                         | 7.6  | 9.5       | 11.4      | nC    |
| Q <sub>gs</sub>             | Gate Source Charge                    |                                                                                         | 2    | 2.7       | 3.2       | nC    |
| Q <sub>gd</sub>             | Gate Drain Charge                     |                                                                                         | 3    | 5         | 7         | nC    |
| t <sub>D(on)</sub>          | Turn-On DelayTime                     | V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =1Ω,<br>R <sub>GEN</sub> =3Ω |      | 6.5       |           | ns    |
| t <sub>r</sub>              | Turn-On Rise Time                     |                                                                                         |      | 2         |           | ns    |
| t <sub>D(off)</sub>         | Turn-Off DelayTime                    |                                                                                         |      | 17        |           | ns    |
| t <sub>f</sub>              | Turn-Off Fall Time                    |                                                                                         |      | 3.5       |           | ns    |
| t <sub>rr</sub>             | Body Diode Reverse Recovery Time      | I <sub>F</sub> =15A, dI/dt=500A/μs                                                      | 7    | 8.7       | 10.5      | ns    |
| Q <sub>rr</sub>             | Body Diode Reverse Recovery Charge    | I <sub>F</sub> =15A, dI/dt=500A/μs                                                      | 11   | 13.5      | 16        | nC    |

A. The value of R<sub>thJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150° C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub>=25° C.

D. The R<sub>thJA</sub> is the sum of the thermal impedance from junction to lead R<sub>thJL</sub> and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150° C. The SOA curve provides a single pulse rating.

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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

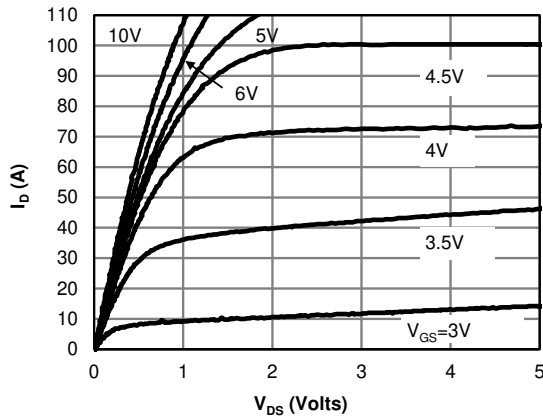


Fig 1: On-Region Characteristics (Note E)

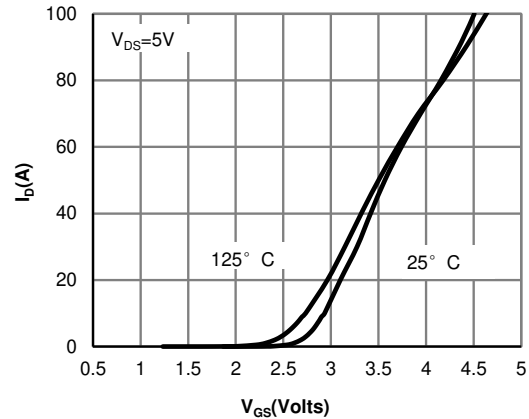


Figure 2: Transfer Characteristics (Note E)

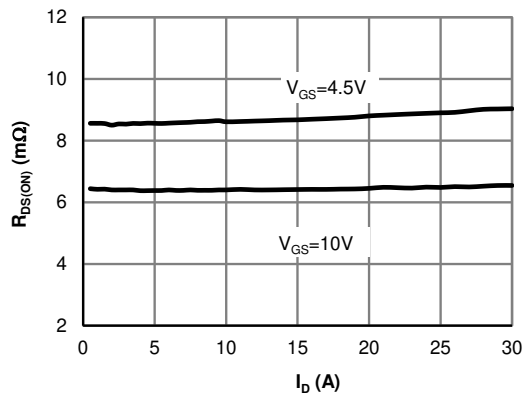


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

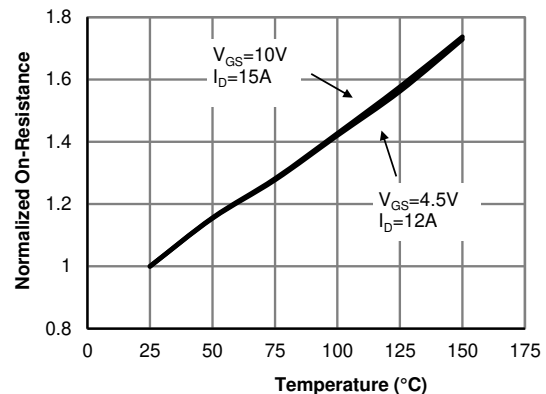


Figure 4: On-Resistance vs. Junction Temperature (Note E)

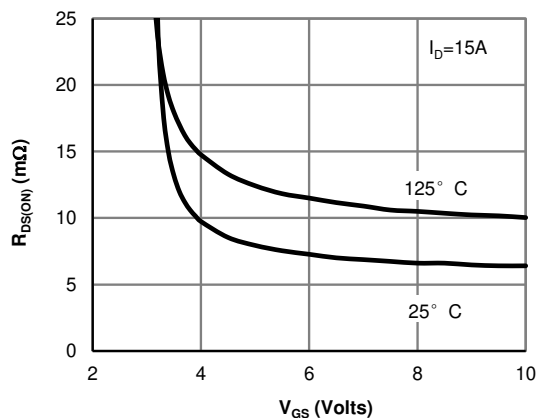


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

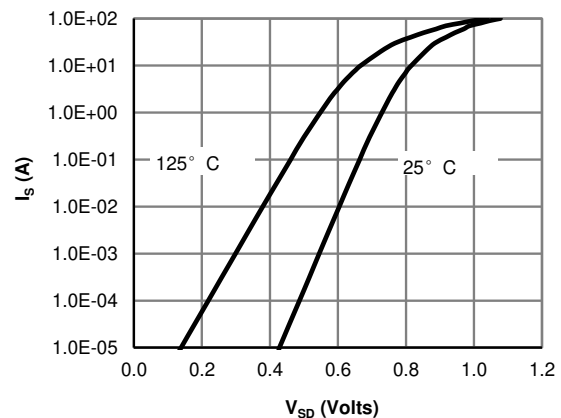
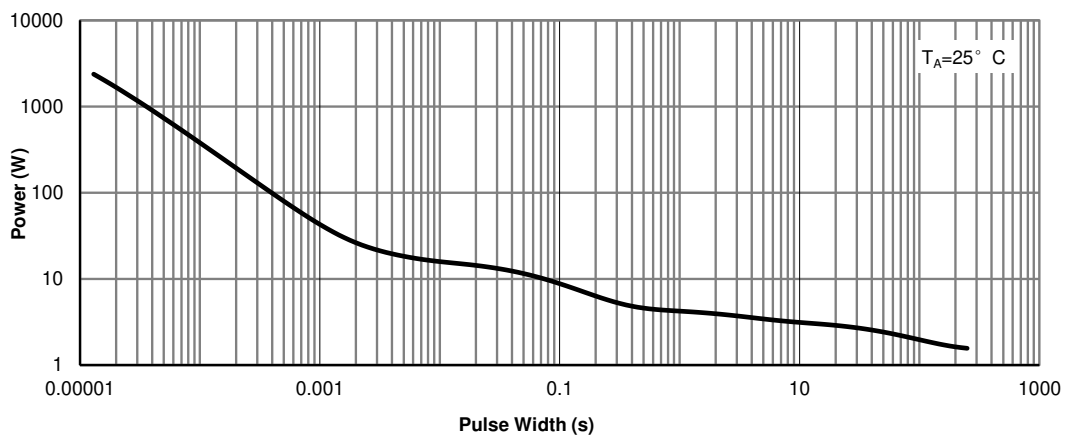
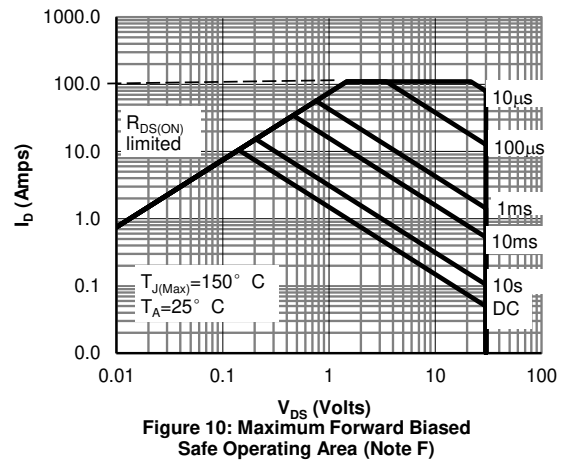
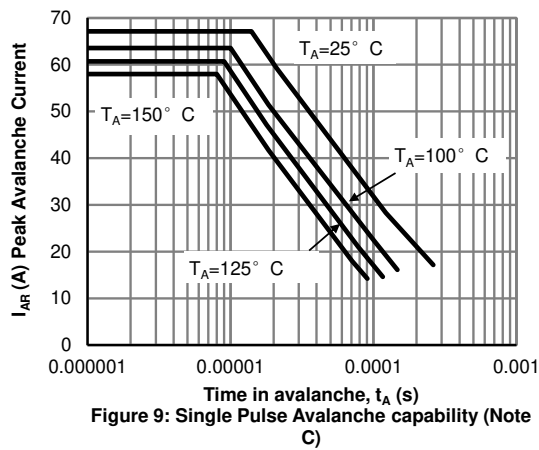
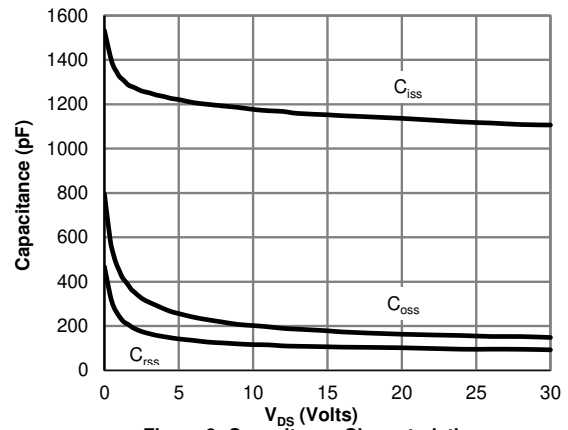
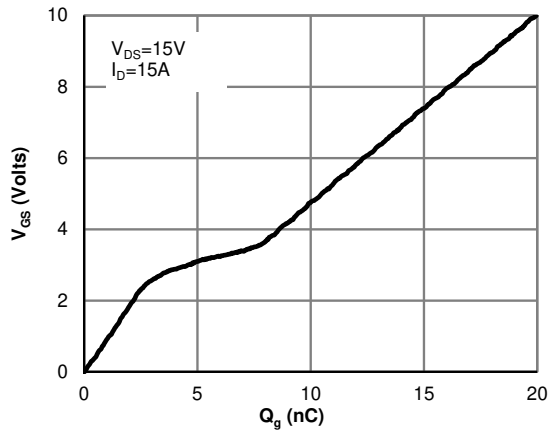
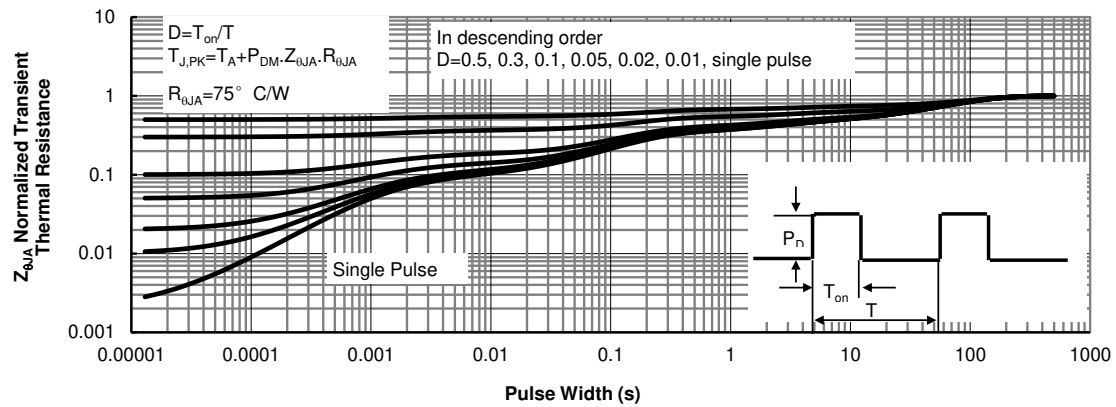


Figure 6: Body-Diode Characteristics (Note E)

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

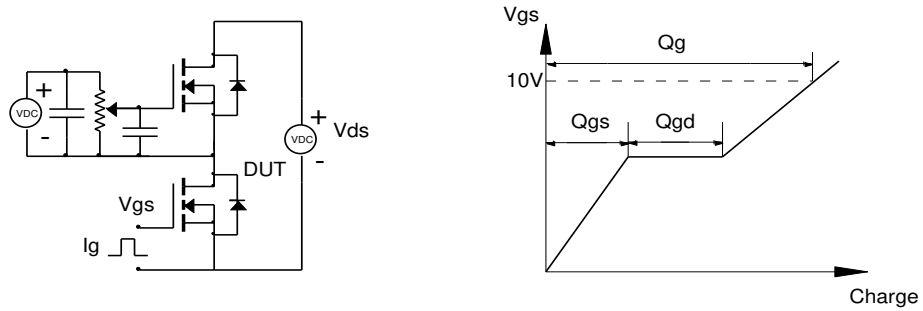


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

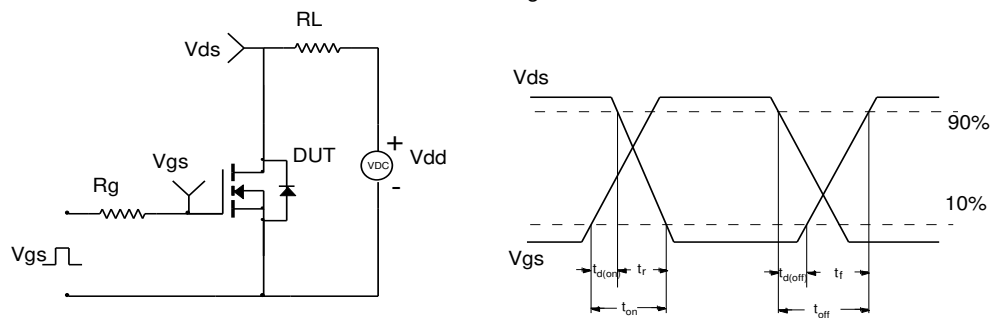


**Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)**

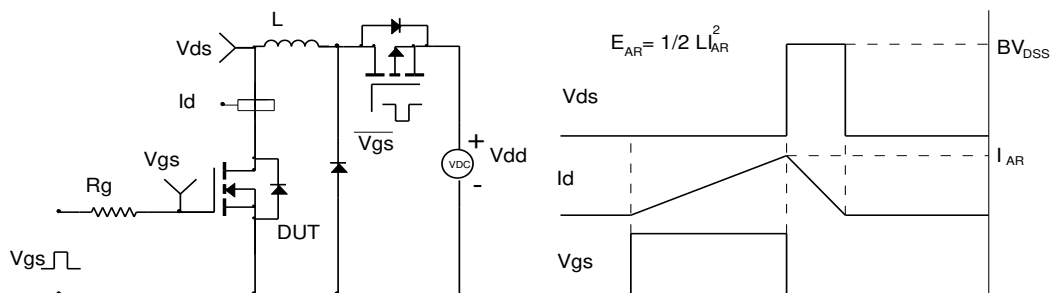
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

